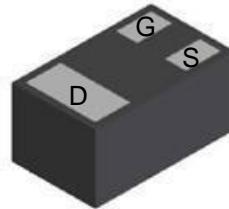


WNM2046

Single N-Channel, 20V, 0.71A, Power MOSFET

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

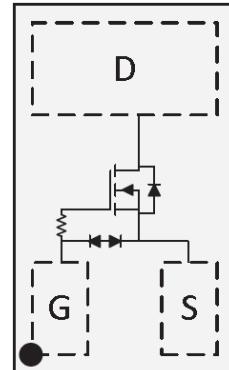
| V_{DS} (V) | Typical R_{DS(on)} (Ω) |
|---------------------------|---------------------------------------|
| 20 | 0.220@ V _{GS} =4.5V |
| | 0.260@ V _{GS} =2.5V |
| | 0.315@ V _{GS} =1.8V |



DFN1006-3L

Descriptions

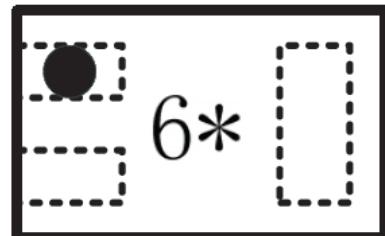
The WNM2046 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R_{DS (ON)} with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM2046 is Pb-free.



Pin configuration (Top view)

Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package DFN1006-3L



6 = Device Code
* = Month (A~Z)

Marking

Applications

- Small Signal Switching
- Small Moto Driver

Order information

| Device | Package | Shipping |
|---------------|----------------|-----------------|
| WNM2046-3/TR | DFN1006-3L | 10K/Reel&Tape |

Absolute Maximum ratings

| Parameter | Symbol | 10 S | Steady State | Unit |
|--|----------------------|----------------|--------------|------|
| Drain-Source Voltage | V _{DS} | 20 | ±5 | V |
| Gate-Source Voltage | V _{GS} | ±5 | | |
| Continuous Drain Current ^{a d} | T _A =25°C | I _D | 0.71 | 0.66 |
| | T _A =70°C | | 0.57 | 0.52 |
| Maximum Power Dissipation ^{a d} | T _A =25°C | P _D | 0.32 | 0.27 |
| | T _A =70°C | | 0.20 | 0.17 |
| Continuous Drain Current ^{b d} | T _A =25°C | I _D | 0.67 | 0.62 |
| | T _A =70°C | | 0.54 | 0.50 |
| Maximum Power Dissipation ^{b d} | T _A =25°C | P _D | 0.28 | 0.24 |
| | T _A =70°C | | 0.18 | 0.15 |
| Pulsed Drain Current ^c | I _{DM} | | 1.4 | A |
| Operating Junction Temperature | T _J | | 150 | °C |
| Lead Temperature | T _L | | 260 | °C |
| Storage Temperature Range | T _{stg} | | -55 to 150 | °C |

Thermal resistance ratings

| Parameter | Symbol | Typical | Maximum | Unit |
|---|------------------|------------------|---------|------|
| Junction-to-Ambient Thermal Resistance ^a | t ≤ 10 s | R _{θJA} | 350 | 390 |
| | Steady State | | 395 | 455 |
| Junction-to-Ambient Thermal Resistance ^b | t ≤ 10 s | R _{θJA} | 397 | 435 |
| | Steady State | | 445 | 505 |
| Junction-to-Case Thermal Resistance | R _{θJC} | 240 | 280 | °C/W |

a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper

b Surface mounted on FR4 board using minimum pad size, 1oz copper

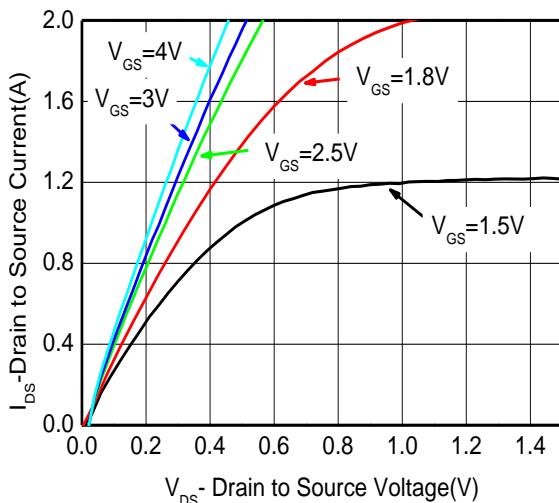
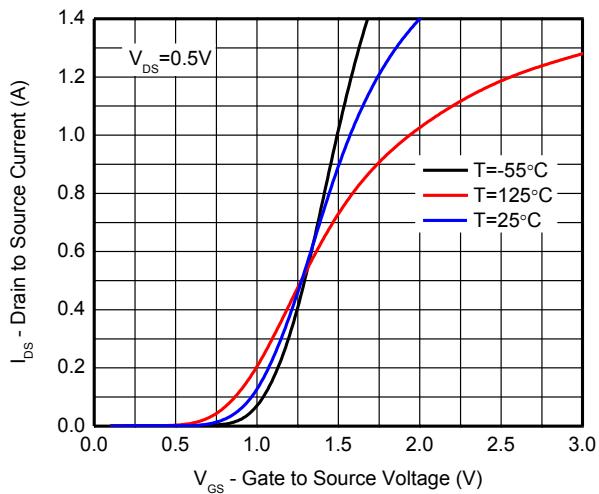
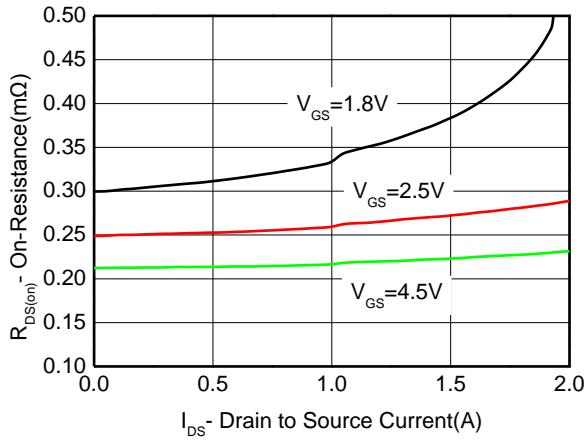
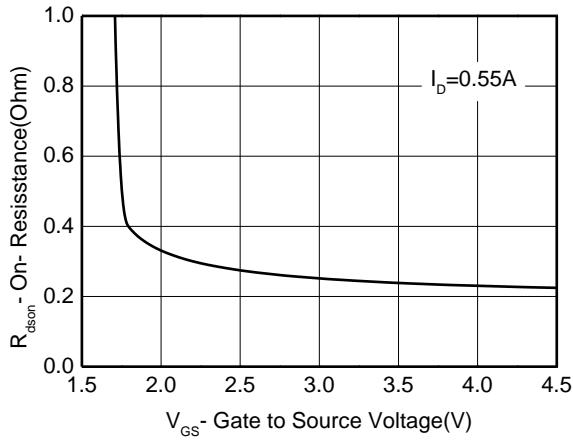
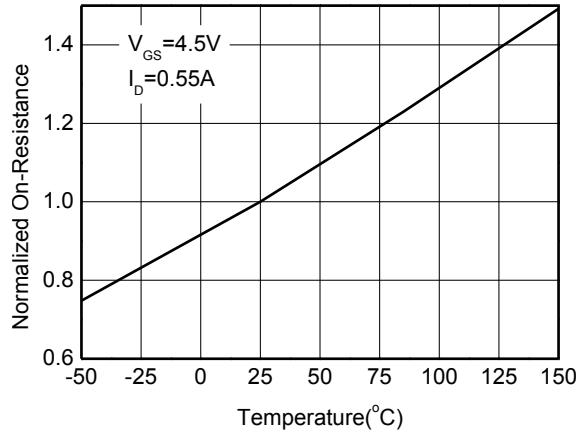
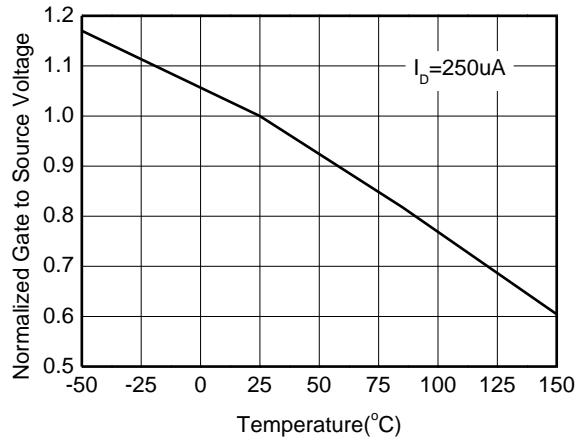
c Pulse width<380μs, Single pulse

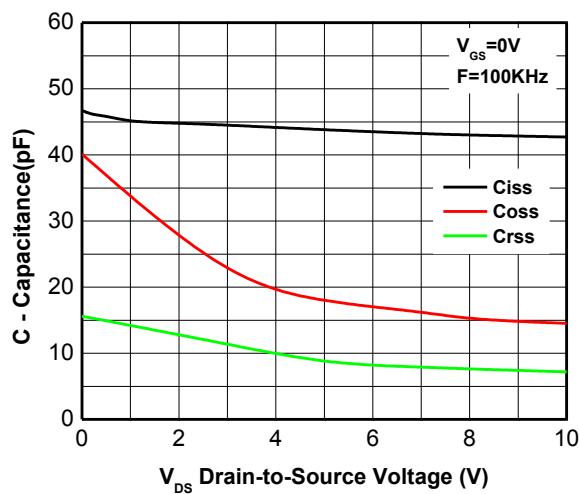
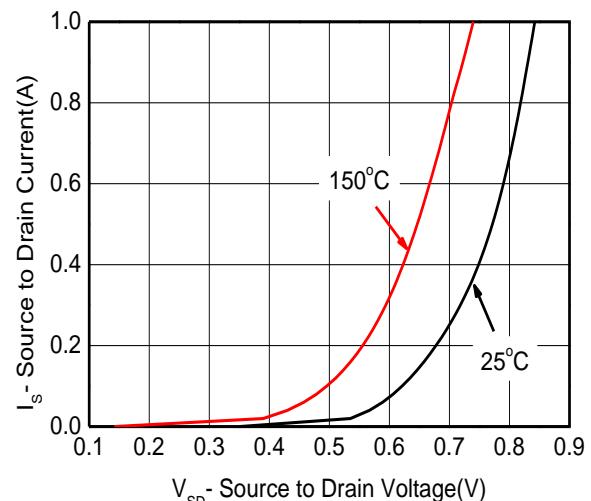
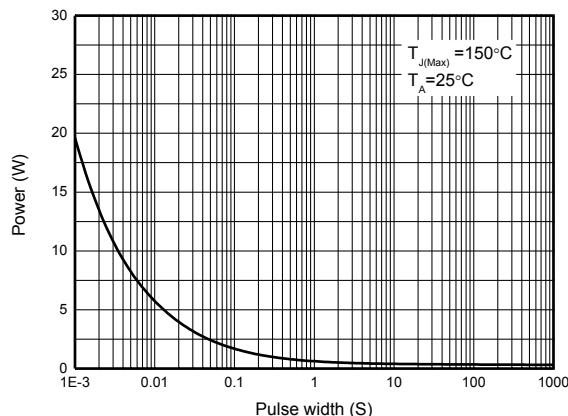
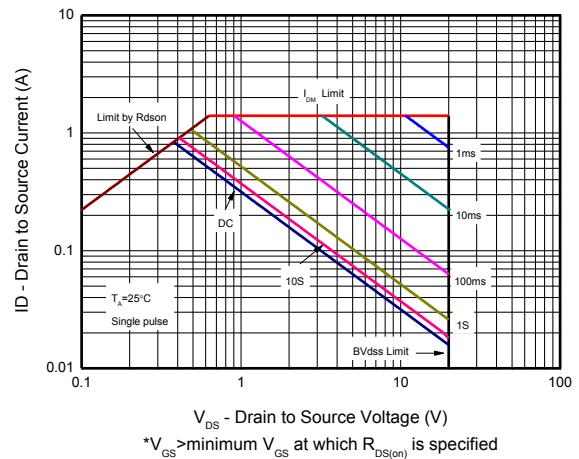
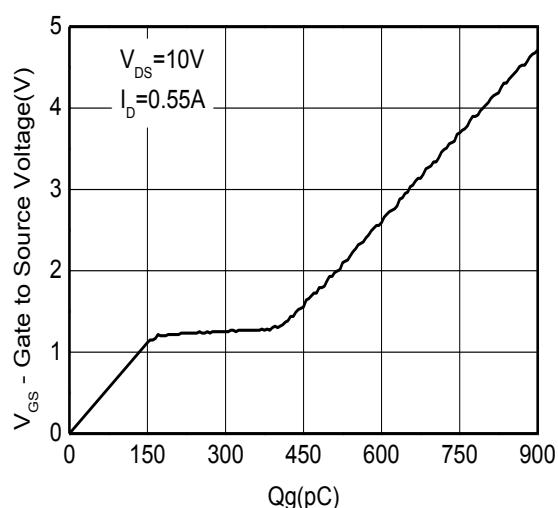
d Maximum junction temperature T_J=150° C.

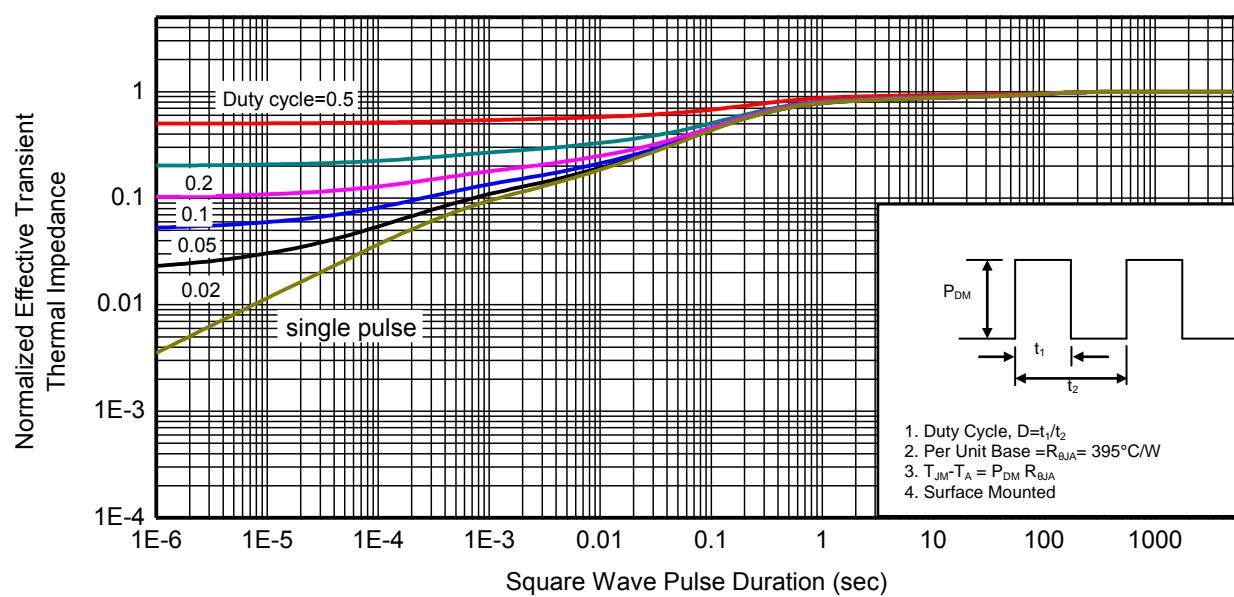
e Pulse test: Pulse width <380 us duty cycle <2%.

Electronics Characteristics (Ta=25°C, unless otherwise noted)

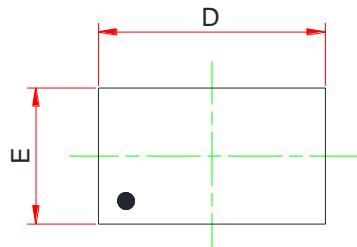
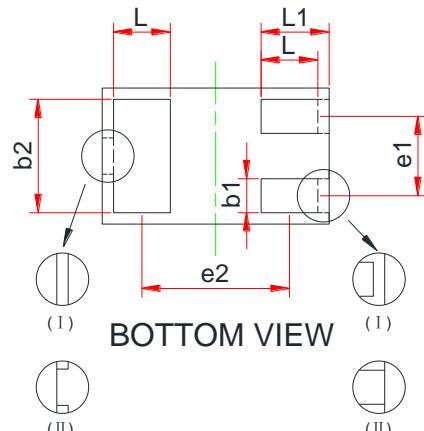
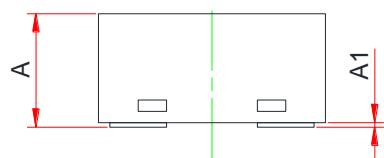
| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|--|------------------|--|------|------|---------|------------------|
| OFF CHARACTERISTICS | | | | | | |
| Drain-to-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0 \text{ V}, I_D = 250\mu\text{A}$ | 20 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 16 \text{ V}, V_{GS} = 0\text{V}$ | | | 1 | μA |
| Gate-to-source Leakage Current | I_{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 5\text{V}$ | | | ± 5 | μA |
| ON CHARACTERISTICS | | | | | | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ | 0.45 | 0.58 | 0.85 | V |
| Drain-to-source On-resistance ^e | $R_{DS(on)}$ | $V_{GS} = 4.5\text{V}, I_D = 0.55\text{A}$ | | 220 | 420 | $\text{m}\Omega$ |
| | | $V_{GS} = 2.5\text{V}, I_D = 0.45\text{A}$ | | 260 | 500 | |
| | | $V_{GS} = 1.8\text{V}, I_D = 0.35\text{A}$ | | 315 | 600 | |
| Forward Transconductance | g_{FS} | $V_{DS} = 5 \text{ V}, I_D = 0.55\text{A}$ | | 2.0 | | S |
| CHARGES, CAPACITANCES AND GATE RESISTANCE | | | | | | |
| Input Capacitance | C_{ISS} | $V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}, V_{DS} = 10 \text{ V}$ | | 50.6 | | pF |
| Output Capacitance | C_{OSS} | | | 13.2 | | |
| Reverse Transfer Capacitance | C_{RSS} | | | 8.3 | | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}, I_D = 0.55\text{A}$ | | 0.87 | | nC |
| Threshold Gate Charge | $Q_{G(TH)}$ | | | 0.06 | | |
| Gate-to-Source Charge | Q_{GS} | | | 0.15 | | |
| Gate-to-Drain Charge | Q_{GD} | | | 0.27 | | |
| SWITCHING CHARACTERISTICS | | | | | | |
| Turn-On Delay Time | $td(\text{ON})$ | $V_{GS} = 4.5 \text{ V}, V_{DS} = 10\text{V}, ID=0.55\text{A}, R_G=6 \Omega$ | | 34 | | ns |
| Rise Time | tr | | | 97.6 | | |
| Turn-Off Delay Time | $td(\text{OFF})$ | | | 606 | | |
| Fall Time | tf | | | 318 | | |
| BODY DIODE CHARACTERISTICS | | | | | | |
| Forward Voltage | V_{SD} | $V_{GS} = 0 \text{ V}, I_S = 0.35\text{A}$ | 0.5 | 0.7 | 1.1 | V |

Typical Characteristics (Ta=25°C, unless otherwise noted)

Output characteristics

Transfer characteristics

On-Resistance vs. Drain current

On-Resistance vs. Gate-to-Source voltage

On-Resistance vs. Junction temperature

Threshold voltage vs. Temperature


Capacitance

Body diode forward voltage

Single pulse power

Safe operating power


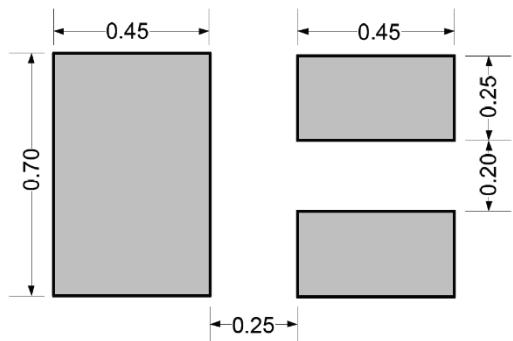


Transient thermal response (Junction-to-Ambient)

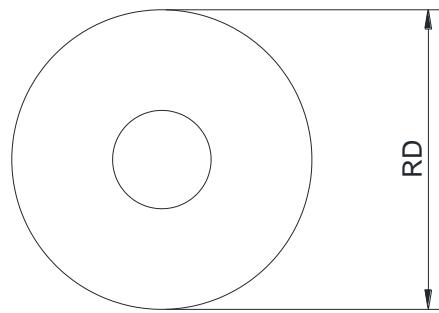
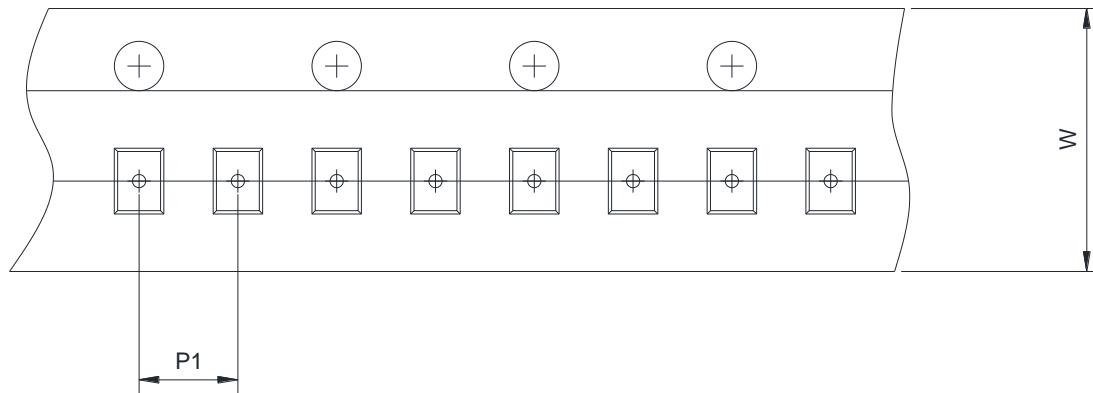
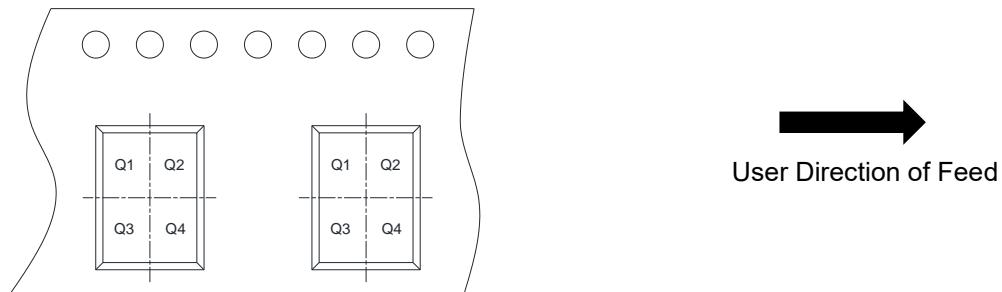
PACKAGE OUTLINE DIMENSIONS
DFN1006-3L

TOP VIEW

BOTTOM VIEW

SIDE VIEW

| Symbol | Dimensions in Millimeters | | |
|--------|---------------------------|------|------|
| | Min. | Typ. | Max. |
| A | 0.36 | - | 0.50 |
| A1 | 0.00 | - | 0.05 |
| D | 0.95 | 1.00 | 1.05 |
| E | 0.55 | 0.60 | 0.65 |
| b1 | 0.10 | 0.15 | 0.20 |
| b2 | 0.40 | 0.50 | 0.60 |
| L | 0.20 | 0.25 | 0.30 |
| L1 | 0.20 | 0.30 | 0.40 |
| e1 | 0.35Ref | | |
| e2 | 0.65 Ref | | |

Recommend land pattern (Unit: mm)



Note: This land pattern is for your reference only. Actual pad layouts may vary depending on application.

TAPE AND REEL INFORMATION
Reel Dimensions
Reel Dimensions

Tape Dimensions

Quadrant Assignments For PIN1 Orientation In Tape


| | | |
|------|---|--|
| RD | Reel Dimension | <input checked="" type="checkbox"/> 7inch <input type="checkbox"/> 13inch |
| W | Overall width of the carrier tape | <input checked="" type="checkbox"/> 8mm <input type="checkbox"/> 12mm <input type="checkbox"/> 16mm |
| P1 | Pitch between successive cavity centers | <input checked="" type="checkbox"/> 2mm <input type="checkbox"/> 4mm <input type="checkbox"/> 8mm |
| Pin1 | Pin1 Quadrant | <input type="checkbox"/> Q1 <input checked="" type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4 |

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[IRS2092STRPBF-EL](#) [IPS70R2K0CEAKMA1](#) [TK31J60W5,S1VQ\(O](#) [TK31J60W,S1VQ\(O](#) [TK16J60W,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#)
[DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [P85W28HP2F-7071](#) [NTE2384](#) [DMC2700UDMQ-7](#) [DMN2080UCB4-7](#) [DMN61D9UWQ-13](#)
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